

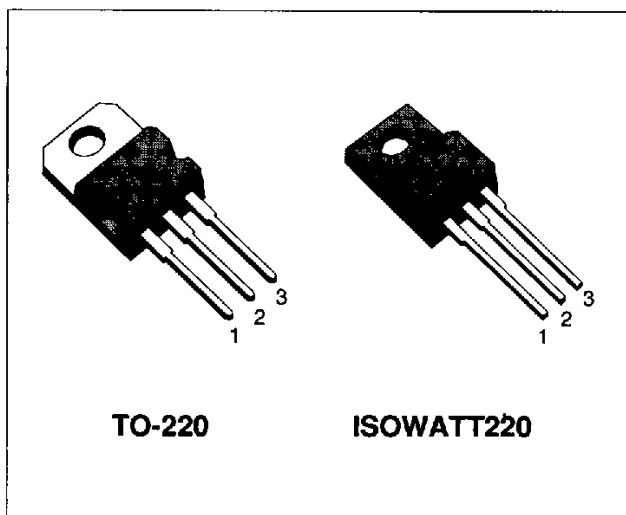
N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTORS

TYPE	V _{DSS}	R _{DS(on)}	I _D
IRF820	500 V	< 3 Ω	3 A
IRF820FI	500 V	< 3 Ω	2.2 A
IRF822	500 V	< 4 Ω	2.8 A
IRF822FI	500 V	< 4 Ω	1.9 A

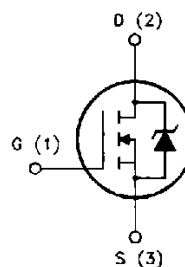
- TYPICAL R_{DS(on)} = 2.5 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C

APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- CHOPPER REGULATORS, CONVERTERS, MOTOR CONTROL, LIGHTING FOR INDUSTRIAL AND CONSUMER ENVIRONMENT



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value				Unit
		IRF				
		820	822	820FI	822FI	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	500	500	500	500	V
V _{DGR}	Drain- gate Voltage (R _{GS} = 20 kΩ)	500	500	500	500	V
V _{GS}	Gate-source Voltage	± 20				V
I _D	Drain Current (cont.) at T _c = 25 °C	3	2.8	2.2	1.9	A
I _D	Drain Current (cont.) at T _c = 100 °C	1.9	1.7	1.4	1.2	A
I _{DM} (*)	Drain Current (pulsed)	12	12	12	12	A
P _{tot}	Total Dissipation at T _c = 25 °C	75		35		W
	Derating Factor	0.6		0.28		W/°C
T _{stg}	Storage Temperature	-65 to 150				°C
T _j	Max. Operating Junction Temperature	150				°C

(*) Pulse width limited by safe operating area



THERMAL DATA

			TO-220	ISOWATT220	
R _{thj-case}	Thermal Resistance Junction-case	Max	1.66	3.57	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient	Max	62.5		°C/W
R _{thc-s}	Thermal Resistance Case-sink	Typ	0.5		°C/W
T _j	Maximum Lead Temperature For Soldering Purpose		300		°C

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max, δ < 1%)	3	A
E _{AS}	Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 25 V)	225	mJ
E _{AR}	Repetitive Avalanche Energy (pulse width limited by T _j max, δ < 1%)	6	mJ
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (T _c = 100 °C, pulse width limited by T _j max, δ < 1%)	1.9	A

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 μA V _{GS} = 0	500			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating x 0.8 T _c = 125 °C			250 1000	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250 μA	2	3	4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10V I _D = 1.5 A for IRF820/820FI for IRF822/822FI		2.5 2.5	3 4	Ω Ω
I _{D(on)}	On State Drain Current	V _{DS} > I _{D(on)} x R _{DS(on)max} V _{GS} = 10 V for IRF820/820FI for IRF822/822FI	3 2.8			A A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} > I _{D(on)} x R _{DS(on)max} I _D = 1.5 A	0.8	1.93		S
C _{iss}	Input Capacitance	V _{DS} = 25 V f = 1 MHz V _{GS} = 0		350	460	pF
C _{oss}	Output Capacitance			60	80	pF
C _{rss}	Reverse Transfer Capacitance			25	35	pF

ELECTRICAL CHARACTERISTICS (continued)
SWITCHING RESISTIVE LOAD

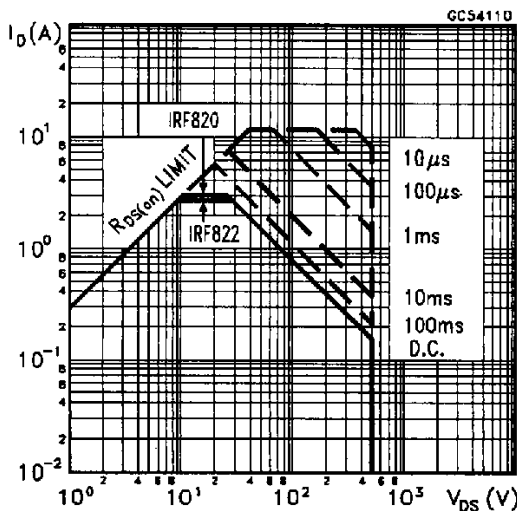
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Time	$V_{DD} = 250\text{ V}$ $I_D = 1.5\text{ A}$		35	45	ns
t_r	Rise Time	$R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$		85	110	ns
$t_{d(off)}$	Turn-off Delay Time	(see test circuit)		165	215	ns
t_f	Fall Time			60	80	ns
Q_g	Total Gate Charge	$I_D = 3\text{ A}$ $V_{GS} = 10\text{ V}$ $V_{DD} = \text{Max Rating} \times 0.8$ (see test circuit)		25 6 11	35	nC nC nC

SOURCE DRAIN DIODE

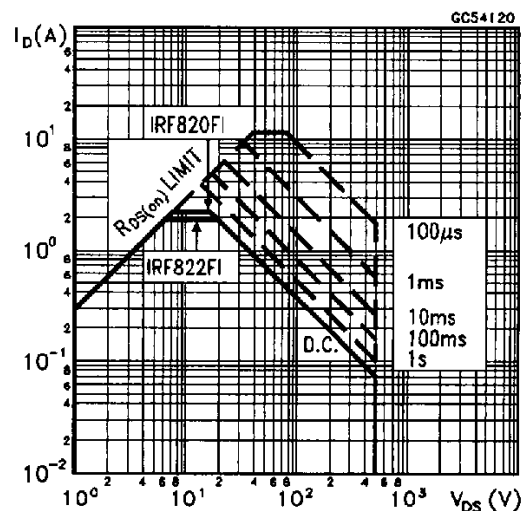
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current				3	A
$I_{SDM}(\bullet)$	Source-drain Current (pulsed)				12	A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 3\text{ A}$ $V_{GS} = 0$			1.6	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 3\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$		380		ns
Q_{rr}	Reverse Recovery Charge			3.8		μC

(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %
 (•) Pulse width limited by safe operating area

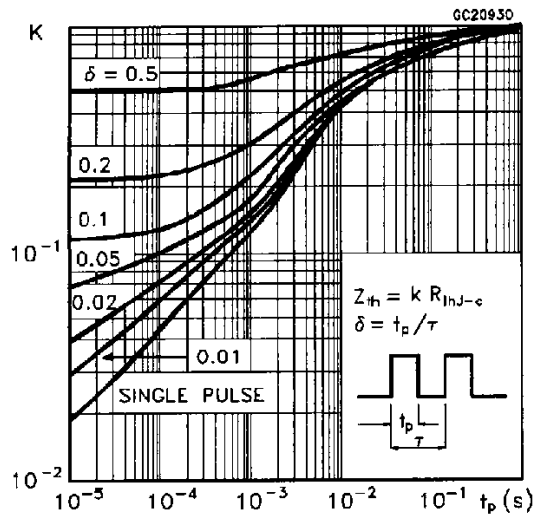
Safe Operating Area for TO-220



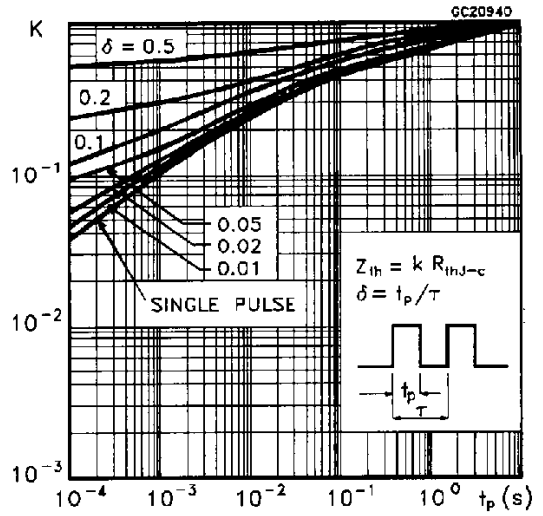
Safe Operating Area for ISOWATT220



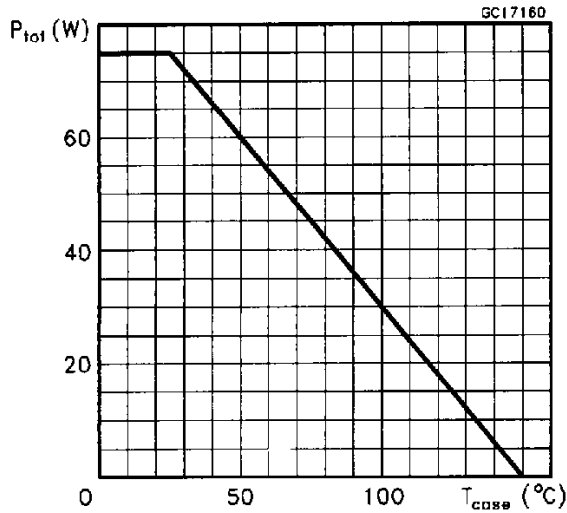
Thermal Impedance for TO-220



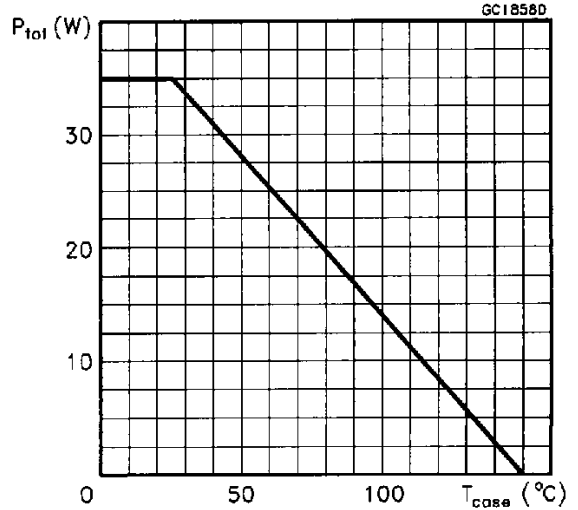
Thermal Impedance for ISOWATT220



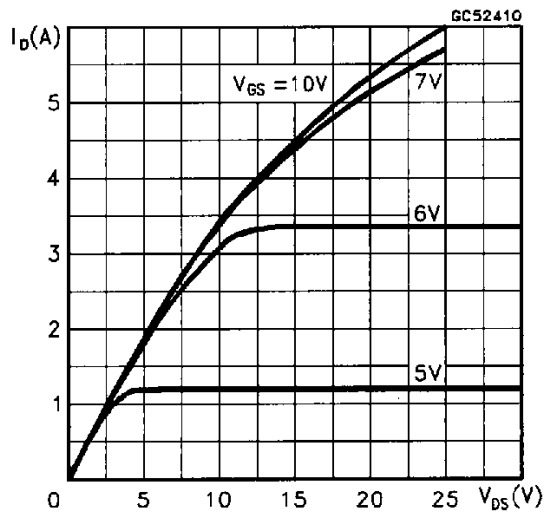
Derating Curve for TO-220



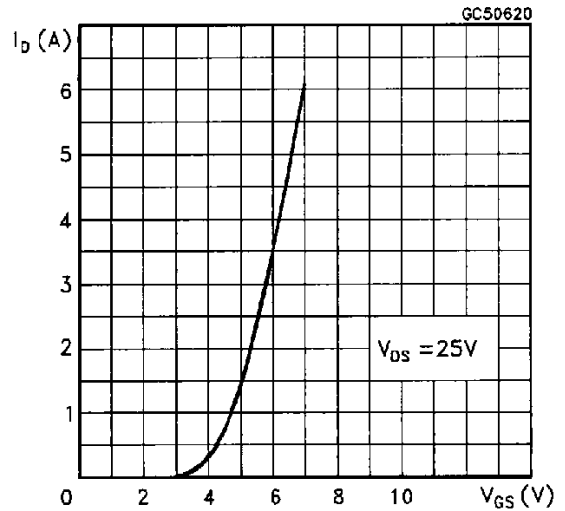
Derating Curve for ISOWATT220



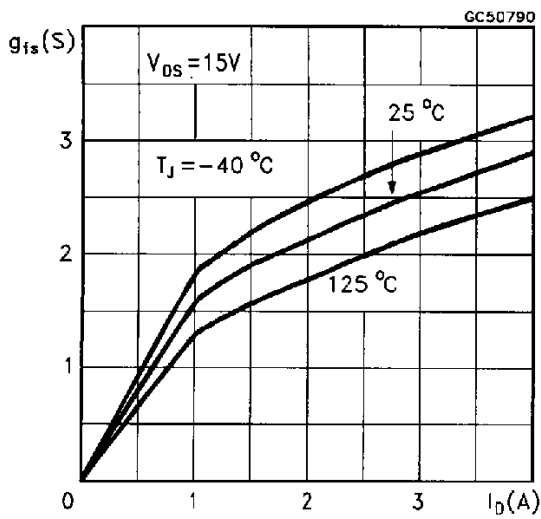
Output Characteristics



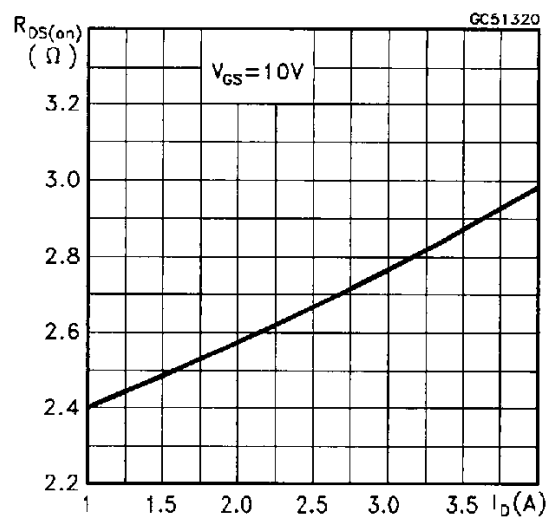
Transfer Characteristics



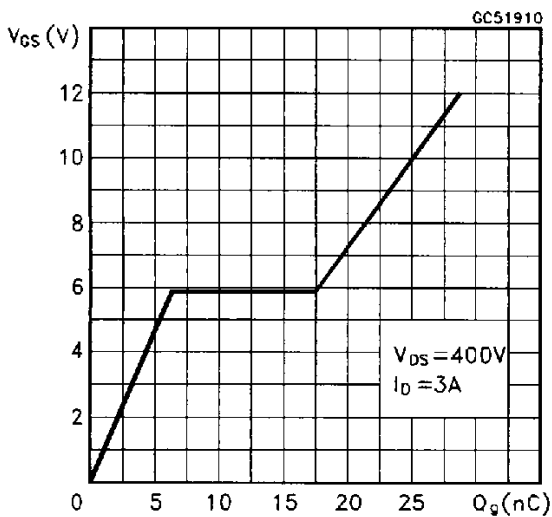
Transconductance



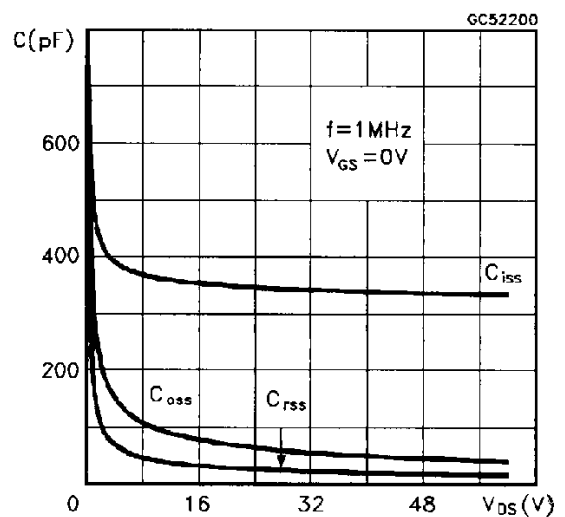
Static Drain-source On Resistance



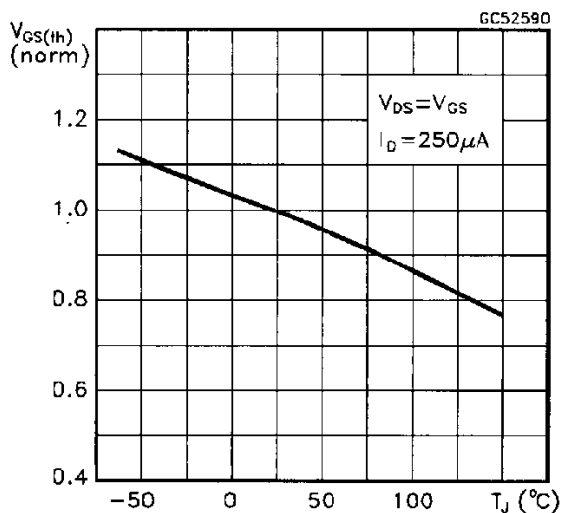
Gate Charge vs Gate-source Voltage



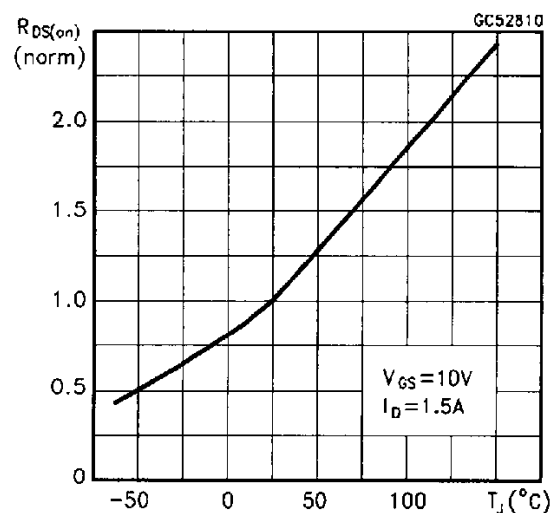
Capacitance Variations



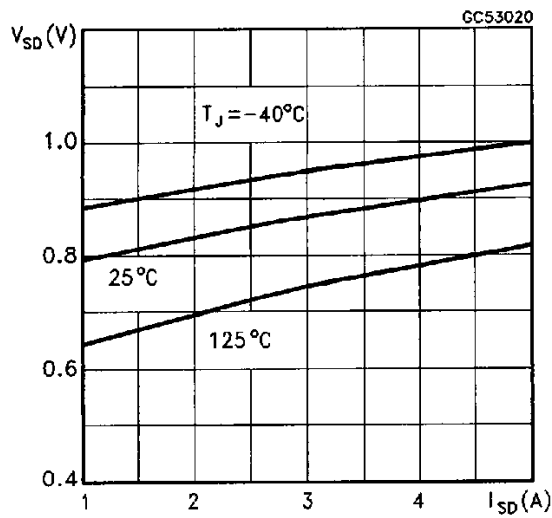
Normalized Gate Threshold Voltage vs Temperature



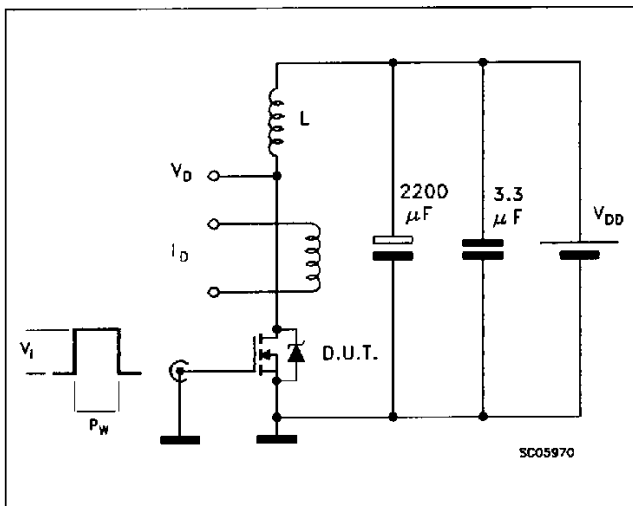
Normalized On Resistance vs Temperature



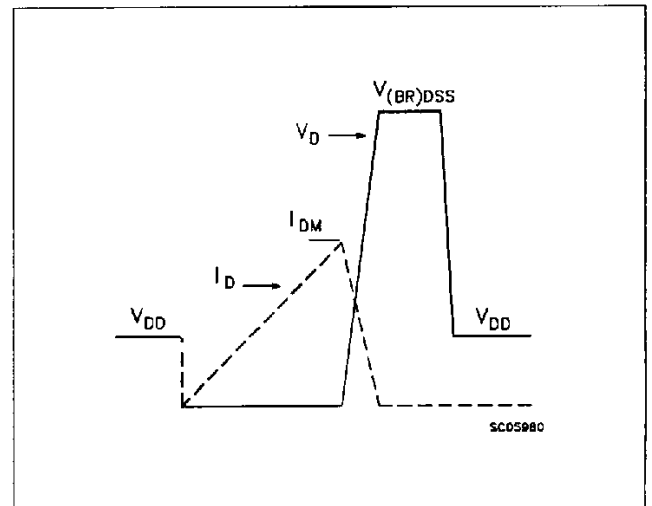
Source-drain Diode Forward Characteristics



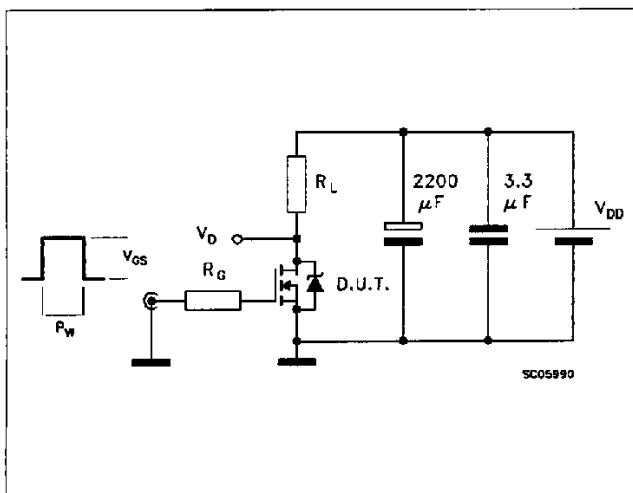
Unclamped Inductive Load Test Circuit



Unclamped Inductive Waveforms



Switching Time Test Circuit



Gate Charge Test Circuit

